



AUTO EQUIPMENT
SOLUTION PROVIDER

萬潤科技

AllRing Tech

Stock Code:6187.TT



Disclaimer

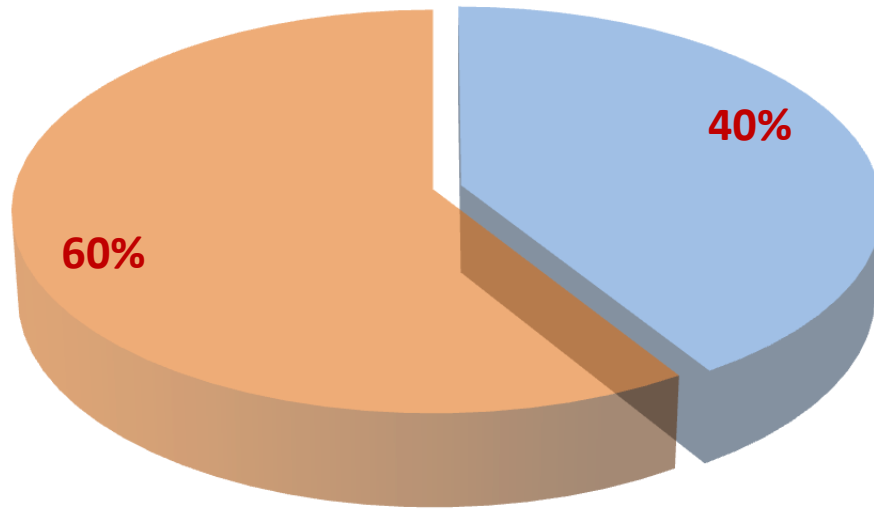
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All prospects reflect Allring-tech expectations toward the future, and may be subject to change and Allring-tech reserves the right to alter, update and change relevant information from time to time without prior notice.

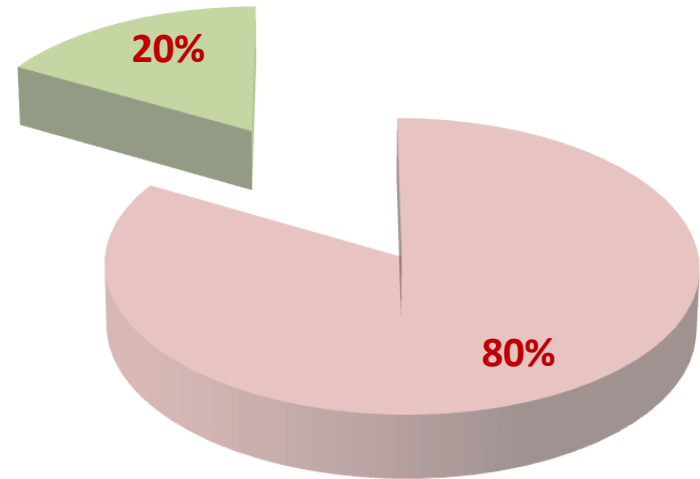
Company Profile

Established	May 24, 1996
Capital	NTD 833 Million (USD 27 Million)
Business	Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing and LED back-end industries
Employee	205 (Feb, 2019)
Chairman	Larry Lu
Address	No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan
Website	www.allring-tech.com.tw

Human Resources- R&D Background





























- Hardware
- Software

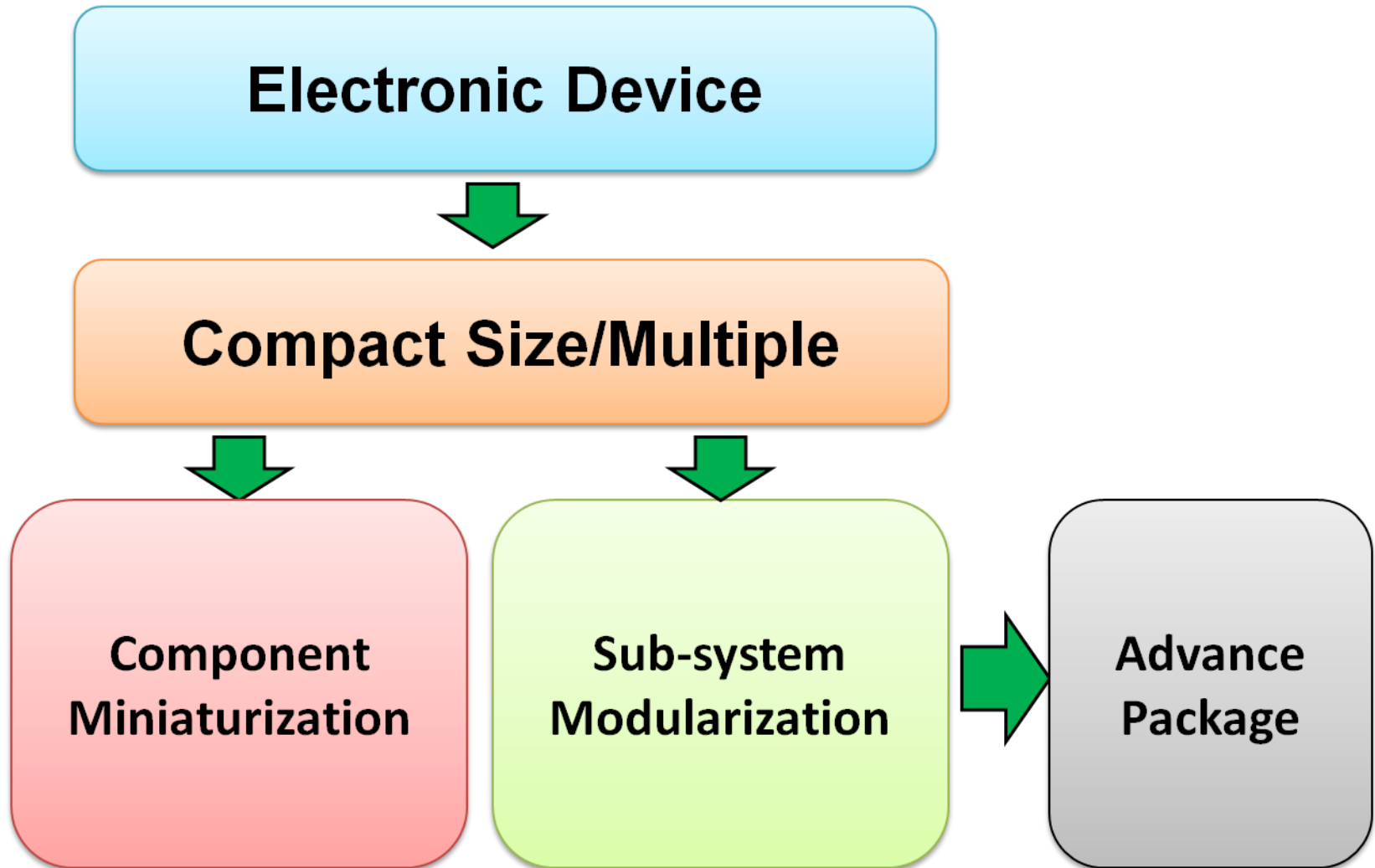


- Motion Programming
- Visual System

Customer Base

Semiconductor	Passive Component	LED
       	           	     

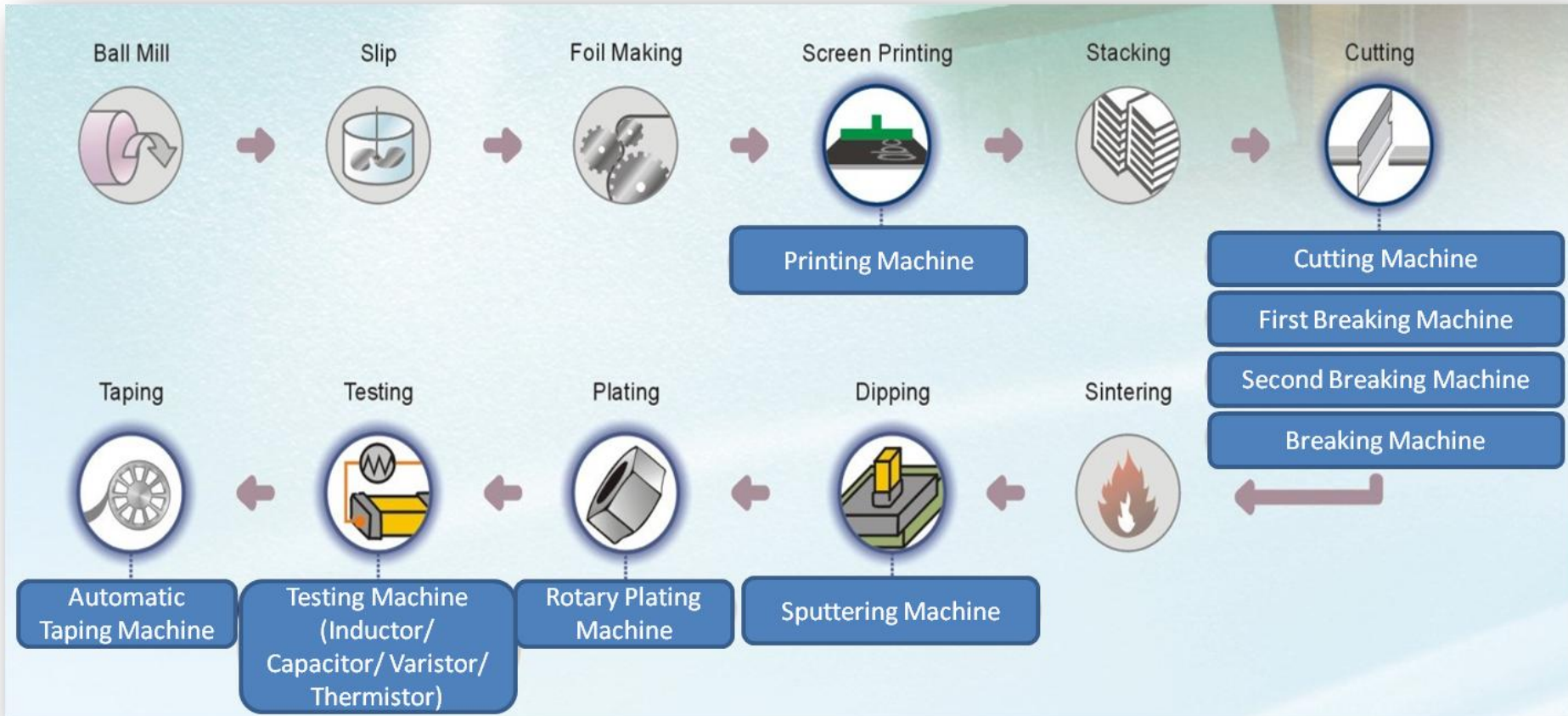
Industry Overview



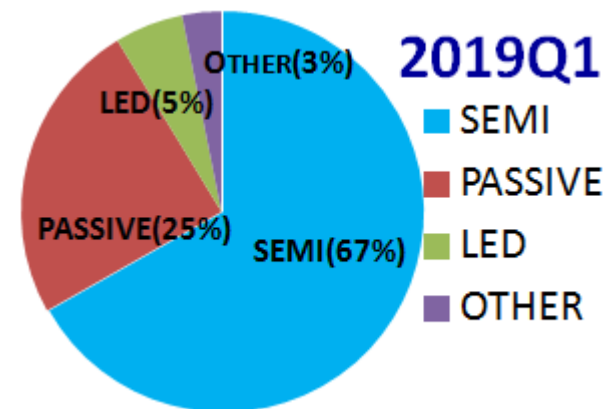
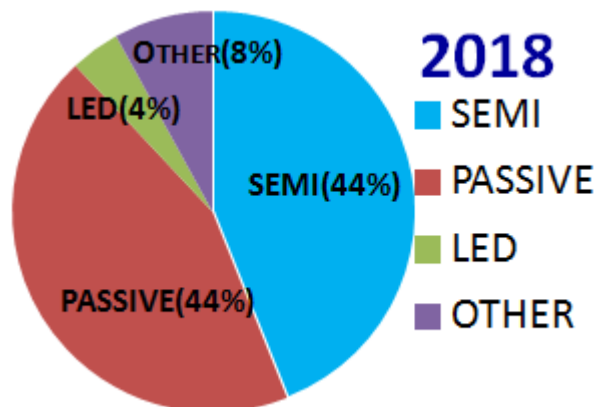
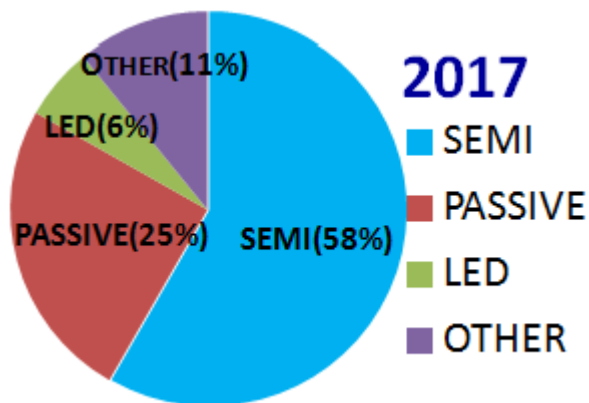
Semi - Advance Package

Packaging Type		Manufacturer		Application
SIP (system in package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	Hon Hai	
			Pegatron	
Component	AAC			
	ICT			
WLP (wafer level package)	InFO	Foundry	TSMC	Smart Phone AI 5G
	CoWoS		TSMC	
Flip chip	2.5/3D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			JCET	
			Powertech	

Passive Component



Revenue Breakdown



NT\$100M

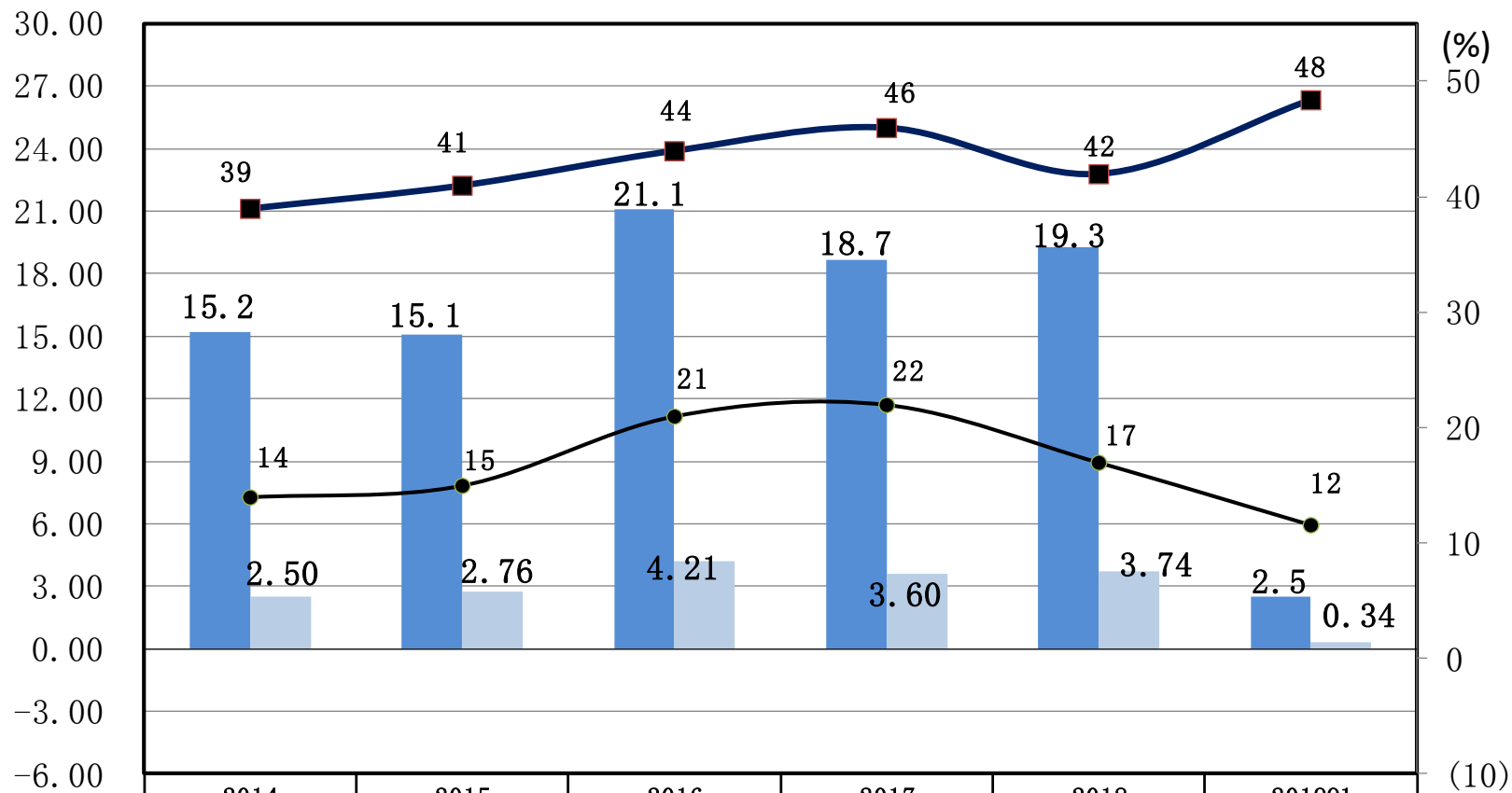
2017

2018

2019Q1

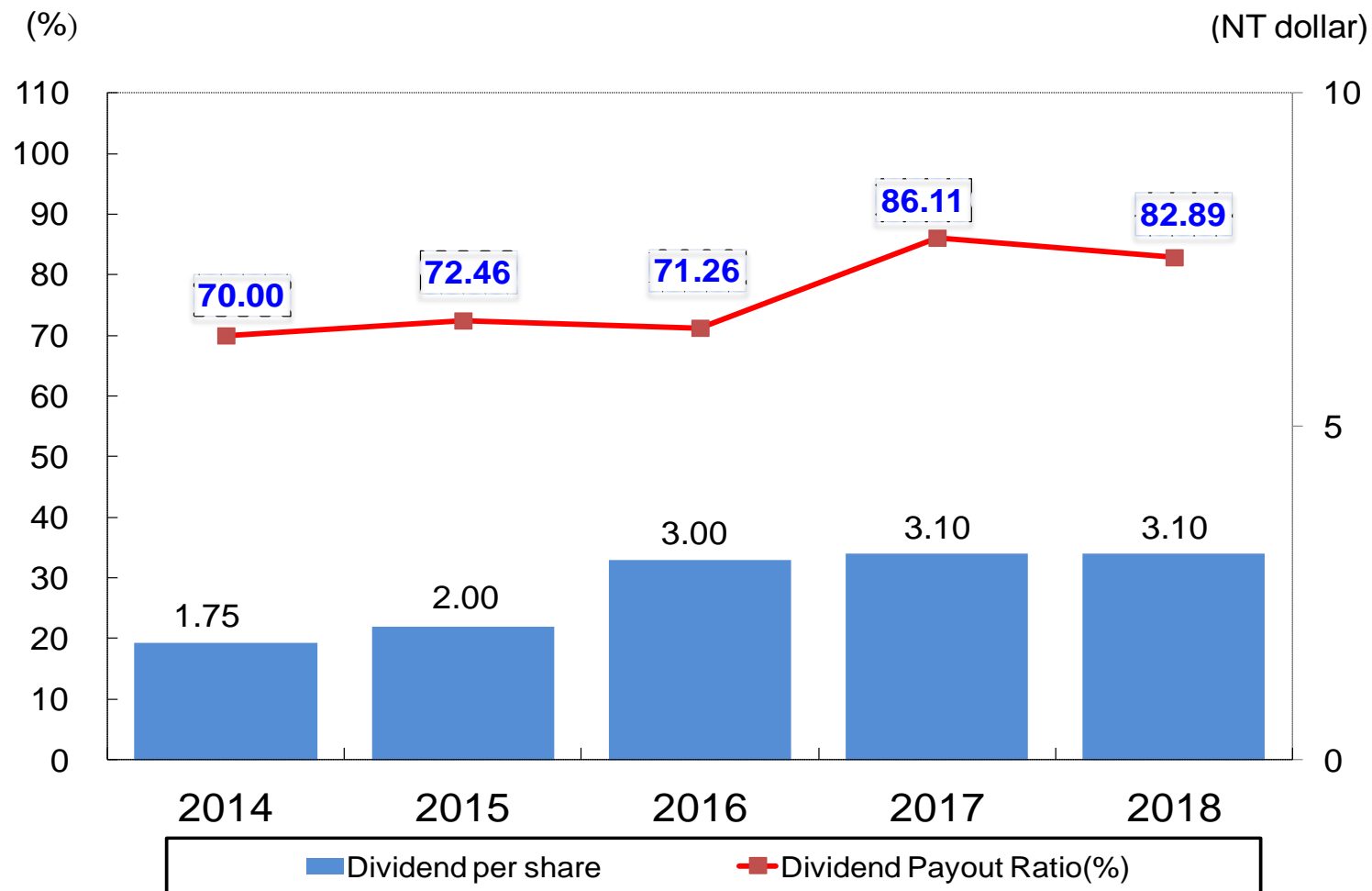
	2017		2018		2019Q1	
SEMI	10.89	58%	8.46	44%	1.69	67%
PASSIVE	4.64	25%	8.49	44%	0.62	25%
LED	1.11	6%	0.77	4%	0.14	5%
OTHER	2.03	11%	1.54	8%	0.08	3%
TOTAL	18.67	100%	19.26	100%	2.53	100%

Financial Highlights

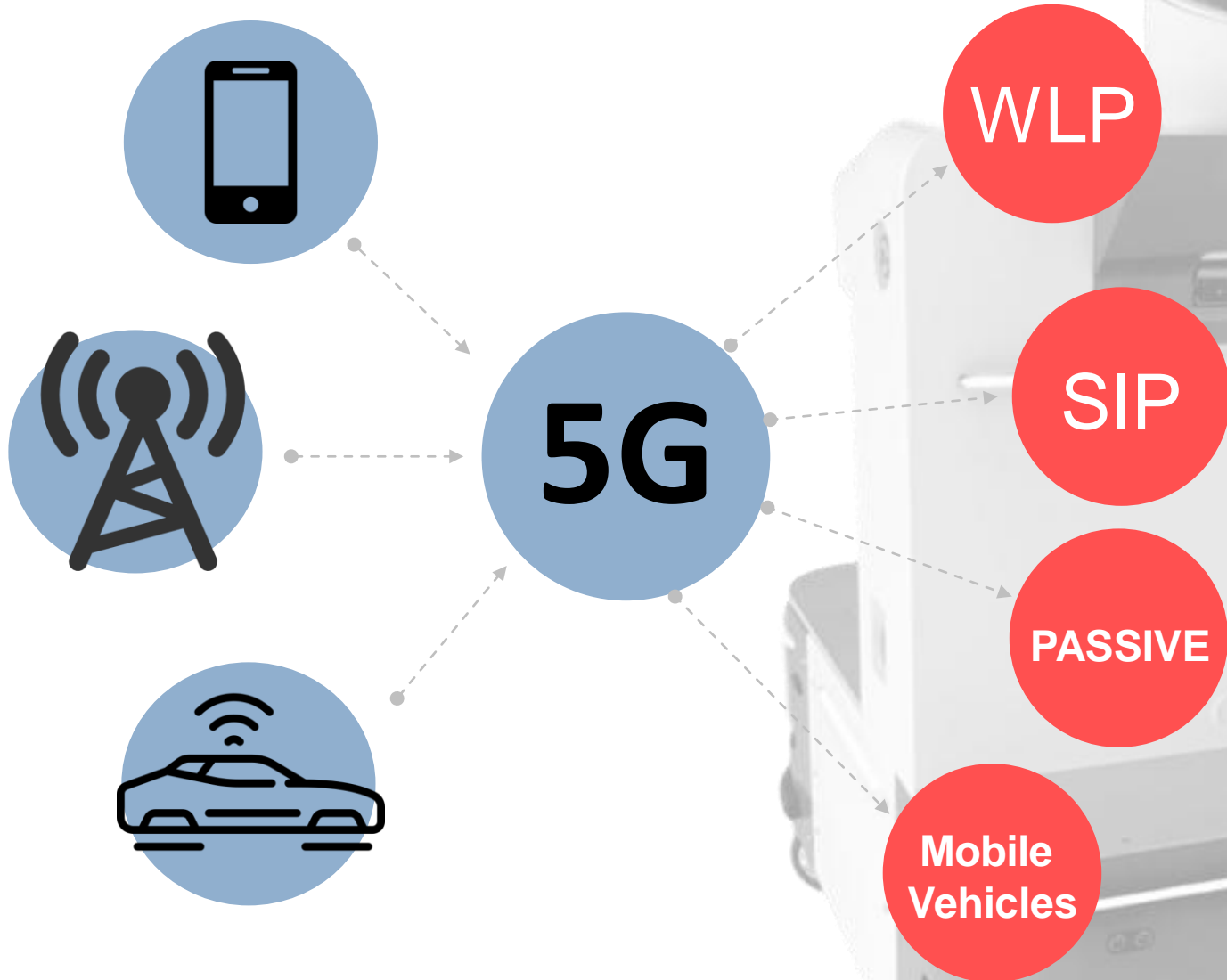


■ Sales (NT\$100mn)	15.2	15.1	21.1	18.7	19.3	2.5
■ EPS (NT\$)	2.5	2.76	4.21	3.60	3.74	0.34
■ GM (%)	39	41	44	46	42	48
● OPM (%)	14	15	21	22	17	12

Financial Highlights



FUTURE APPLICATION





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Thank you